

S102S03/S202S03

SIP Type SSR with Mounting Capability for External Heat Sink

■ Features

1. High radiation resin mold package
2. RMS ON-state current I_T : MAX. 8 Arms at $T_c \leq 80^\circ\text{C}$ (With heat sink)
3. Isolation voltage between input and output (V_{iso} : 4 000V_{rms})
4. Low input driving current (I_{FT} : MAX. 5mA)
5. Approved by CSA, No. LR63705
Recognized by UL, file No. E94758

■ Applications

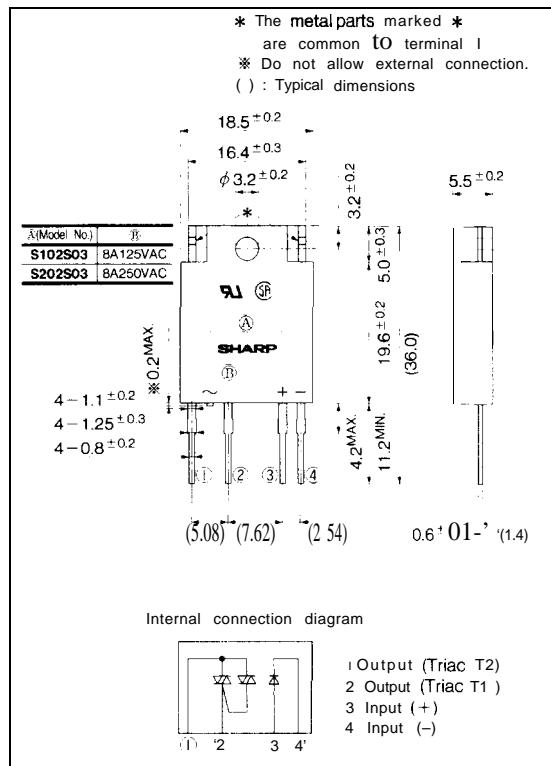
1. Automatic vending machines
2. Programmable controllers
3. Amusement equipment

■ Model Line-ups

For 100V lines	For 200V lines
S102S03	S202S03

■ Outline Dimensions

(Unit : mm)



■ Absolute Maximum Ratings

(Ta = 25°C)

Parameter		Symbol	Rating		Unit
			S102S03	S202S03	
Input	Forward current	I _F	50		mA
	Reverse voltage	V _R	6		V
output	RMS ON-state current	I _T	*48		A _{rms}
	*! Peak one cycle surge current	I _{surge}	80		A
	Repetitive peak OFF-state voltage	V _{DRM}	400	600	V
	Non-repetitive peak OFF-state voltage	V _{DSDM}	400	600	V
	Critical rate of rise of ON-state current	dI _F /dt	50		A / μs (Note)
	Operating frequency	f	45 to 65		Hz
*isolation voltage		V _{iso}	4 000		V _{rms}
	Operating temperature	T _{opr}	-25 to +100		°C
	Storage temperature	T _{stg}	-30 to +125		°C
	soldering temperature	T _{sol}	260		°C

*1 50Hzsinewave, Tj=25°C start
 *2 60Hz AC for 1 minute
 40 to 60%RH, Apply voltages between input and output by the dielectric withstand voltage tester with zero-cross circuit.
 (Input and output shall be shorted respectively).

When the isolation voltage is necessary at using external heat sink, please use the insulation sheet.

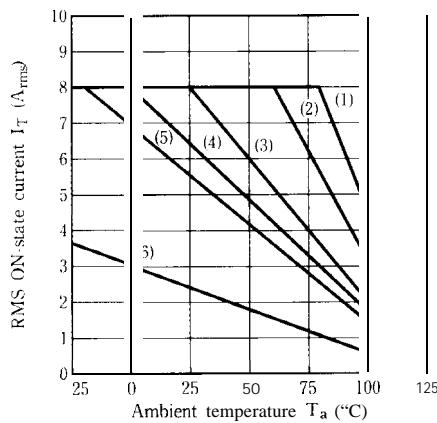
*3 For 1(1 seconds
 *4 T_c ≤ 80°C

■ Electro-optical Characteristics

(Ta = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V _F	I _F = 20mA		1.2	1.4	V
	Reverse current	I _R	V _R = 3V		—	10 ⁻⁶	A
Output	Repetitive peak OFF-state current	I _{DRM}	V _D = V _{DRM}		—	10 ⁻⁴	A
	On-state voltage	V _T	Resistance load, I _F = 20mA I _T = 2A _{rms}	.	—	1.5	V _{rms}
Transfer characteristics	Holding current	I _H			—	35	mA
	Critical rate of rise of OFF-state voltage	dV/dt	V _D = 2/3V _{DRM}	30	—	—	V / μs
	Critical rate of rise of commutating OFF-state voltage	(dV/dt) _C	T _j = 125°C, dI _t /dt = -4.0A/ms. V _D = 400V	.	—	—	V / μs
	Minimum trigger current	I _{FT}	V _D = 12V, R _L = 30Ω	—	—	5	mA
	Isolation resistance	R _{ISO}	DC = 500V, 40 to 60%RH	10 ¹⁰	—	=	Ω
	Turn-on time	t _{on}	AC = 50Hz	—	—	1	ms
	Turn-off time	t _{off}		—	—	10	ms
	Thermal resistance (Between junction and case)	R _{th(j-c)}			4.5	—	°C/W
	Thermal resistance (Between junction and ambience)	R _{th(j-a)}		—	40	—	°C/W

Fig. 1 RMS ON-state Current vs. Ambient Temperature



- (1) With infinite heat sink
 - (2) With heat sink (200×200×2mm Al plate)
 - (3) With heat sink (1 OOX10OX2.. Al plate)
 - (4) With heat sink (75×75×2mm Al plate)
 - (5) With heat sink (50×50×2mm Al plate)
 - (6) Without heat sink
- (Note) With the Al heat sink set up vertically, tighten the device at the center of the Al heat sink with a torque of 0.4N · m and apply thermal conductive silicone grease on the heat sink mounting plate. Forcible cooling shall not be carried out.

Fig. 2 RMS ON-stats Current vs. Case Temperature

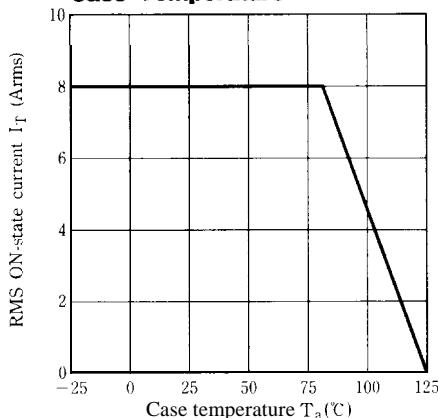


Fig. 4 Forward Current vs. Forward Voltage

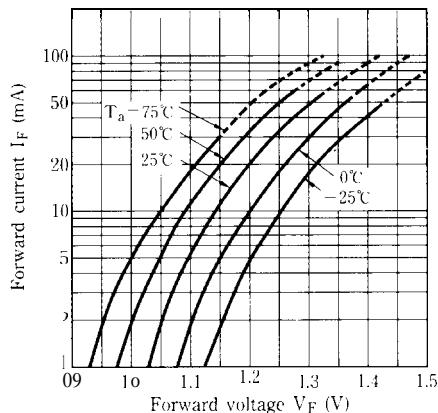


Fig. 6 Maximum ON-state Power Dissipation vs. RMS ON-state current

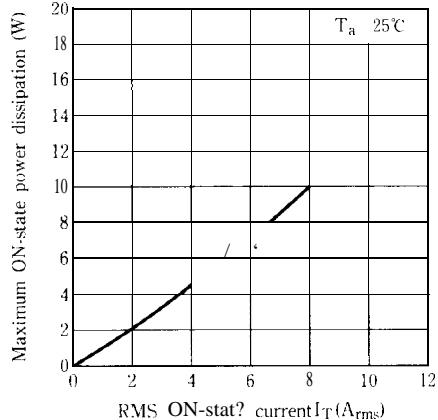


Fig. 3 Forward Current vs. Ambient Temperature

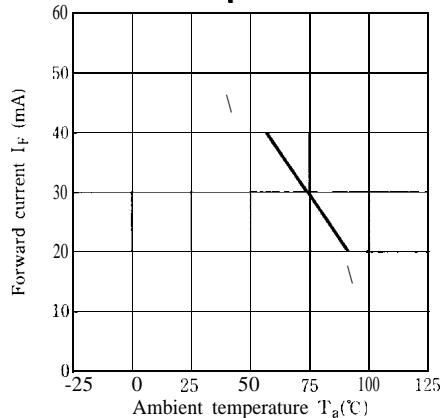


Fig. 5 Surge Current vs. Power-on Cycle

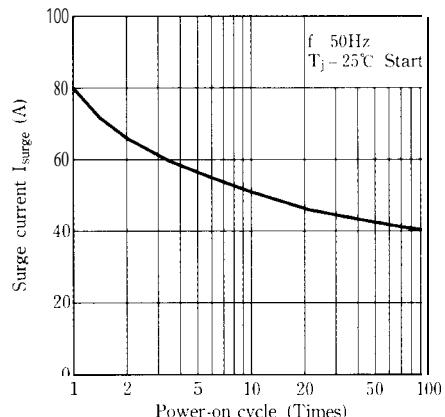


Fig. 7 Minimum Trigger Current vs. Ambient Temperature (Typical Value)

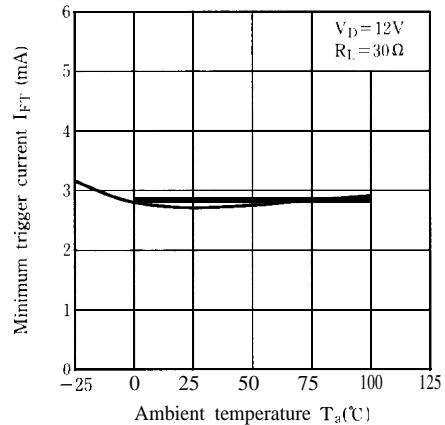


Fig. 8 Relative Repetitive Peak OFF-state Voltage vs. Ambient Temperature (Typical Value)

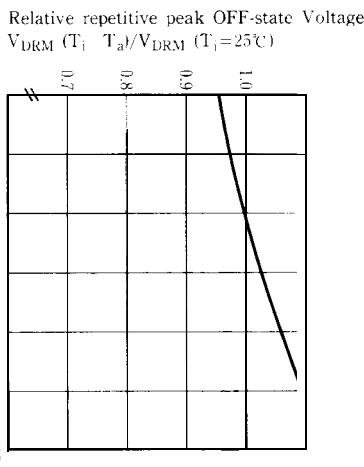


Fig.9-b Repetitive Peak OFF-state Current vs. Ambient Temperature (Typical Value) (S202S03)

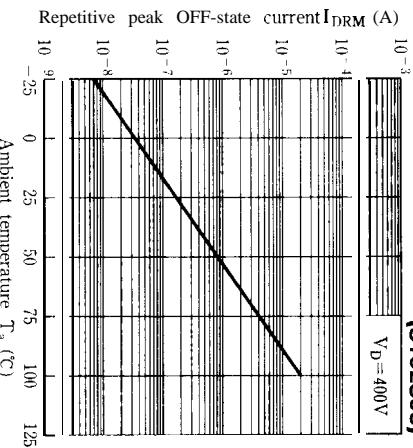
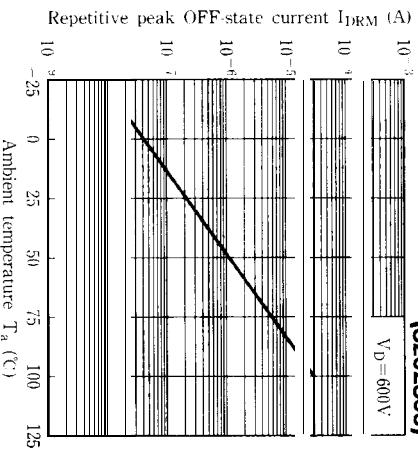


Fig.9-a Repetitive Peak OFF-state Current vs. Ambient Temperature (Typical Value) (S102S03)

- Please refer to the chapter "Precautions for Use" (Page 78 to 93).



Solid State
Relays